LS3E and U2 electronics

Overview
Prototypes
FastRICH
Back-end

LS3E electronics

Replace FE electronics but keep photon sensors same for Run4, new sensors for Run 5

Benefit from longer LS3 to front-load some developments required for Upg2 (25ps time-resolved photon readout)

Minimise other changes (power distribution, cooling infrastructure, mechanical envelope)

Also

- Back-end (pcie40) development
- Reconstruction updates to exploit timing information



Prototype development

Testbeam/lab electronics

Light-weight, modular system developed for lab, beam tests

Successful read out of ca. 500 photon sensor channels

Good timing performance achieved in distributed system

Excellent reliability at high data rate - many millions of events in a few days

Next step – design a FastRICH plug-in



RICH 2024 testbeam

Hardware connections



EC thermal studies

https://indico.cern.ch/event/1427786/ contributions/6005378/attachments/ 2886133/5058317/EC+_FASTRICH_cooling-27062024_SM.pdf

EC thermo-mechanical design

Note: Modifications (even additional screw holes) of existing infrastructure difficult/impossible due to RP requirements

Power load distribution shifts towards EC

Thermal coupling of EC to cold spine is not ideal

Mock-ups of new FastRICH EC under study (Genova)

FastRICH power still uncertain (simulation/ estimation evolving)

Must keep within constraints of existing power budget (Maratons)

EC+ Instrumented





EC+ mounted on Peltier cell.



https://indico.cern.ch/event/1398911/

R	Review 16 th May 2024									
	Analogue									
	TDC									
	Readout									
	ECS									
	Verification									
	September submission									



Analogue



Features Positive or negative polarity Test pulse injection Constant fraction discriminator (CFD) or leading edge discriminator (LED) Programmable gain and threshold Differential signalling (internally)

CFD simulations







FERO (TDC)



Performance

TDC architecture largely verified in recent tests of FastIC+

Excellent DNL (6ps) & INL (+/-22ps), FastIC+

Jitter 14ps, FastIC+

Studies of FERO efficiency vs. clock ratios. 95% of hits from analogue registered.

Dataflow

Status (at review, A. Paternò)

PLL: post-layout characterization done

TDC Block: RTL Done, implementation ongoing

Packet and Frame Builder: RTL almost complete

AURORA: RTL done

Top Digital block: RTL almost complete, triplication and synthesis starting soon



Test environment

Single ASIC functional testing (hardware verification)

Bespoke test station under development (Bucharest)

Semi-automatic testing of MPW devices (100's), wire bonded or QFN88

Add automated ASIC handling for production volumes

Full functional testing to confirm:

- Configuration functionality and reliability
- Analoque performance and CFD
 operation
- TDC operation
- Timing resolution
- Readout functionality for all data lane configurations
- Response of FastRICH to TFC

Yield



Planning

Work needs to start on BE firmware

A few areas identified for priority development (e.g Aurora handling in BE FPGA)

Invite contributors from RICH, ASIC and on-line teams

Contributions also needed to help develop controls software, specify testing protocols and help design testing environments

Define tasks, assign responsibilities and agree timescales

A preliminary meeting of interested parties has taken place – "hands on" session planned in August

Summary of required BE development

LpGBT core implementation for pcie40 (similar to current GBTX core)

Aurora receiver FPGA firmware (FPGA resource-sensitive design)

LHCb data synchronisation logic (response to TFC commands)

RICH data packet building (merging Aurora lanes into events)

Porting of firmware to pcie400 when available

LS3E schedule



RICH - LS3 Enhancement EC

Overall Schedule



		2021			20	22		2023				2024				2025				2026					20)27		2028			
	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4
R&D																								102.0				12.5			
Initial FastRICH des and specs																								-33 3	art a	na au	ratio	1(3.5	years		
First prototype readout dev.																															
Test Beam 1																															
Test Beam 2																															
Tech Design Report																															
Test Beam 3																															
FastRICH												М	PW		exp																
EC and Front-end readout design																evn	2														
PDM design and proto tests																evh															
Test Beam 4																															
DAQ and Firmwares																															
Engineering Design Report (EDR)																															
FastRICH final ASIC																FastR	ICH fina	al ASIC													
Test Column Ready (MWP), full enhanc	(EDR) I <td colspan="5"></td>																														
Test Column Ready (MWP), de-scoping 1												enhance RICH 1																			
Test Column Ready (MWP), de-scoping 2	n Ready (MWP), de-scoping 1 n Ready (MWP), de-scoping 2 n Ready (MWP), de-scoping 2 n Ready (MWP), de-scoping 3 n Ready (MWP), de-scoping 3 n Ready (MWP), de-scoping 3 n Ready (MWP) (MWP																						enhance RICH 2								
Test Column Ready (MWP), de-scoping 3																												enh e	xtra 4 (cols in I	RICH 2
Full Enhancement																															
Production Design Report (PRR)																															
Test Beam 5																															
Production																															
QA												De	sign		Proto	types															
ComLab																															
Installation																															
Commissioning at Point 8																															
Ready for Beams																															
Soft, Sim, Det., PID, Perf.																															